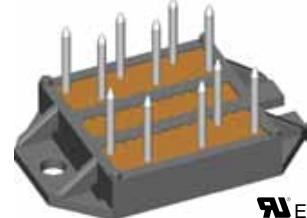
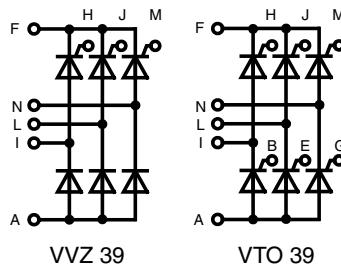


## Three Phase Rectifier Bridge

 $I_{dAV} = 39 \text{ A}$   
 $V_{RRM} = 800/1200 \text{ V}$ 

## Preliminary data

$V_{RSM}$	$V_{RRM}$	Type
$V_{DSM}$	$V_{DRM}$	
V	V	
900	800	VTO 39-08ho7
1300	1200	VTO 39-12ho7
		VVZ 39-08ho7
		VVZ 39-12ho7



E72873

Pin arrangement see outlines

Symbol	Conditions	Maximum Ratings			Features
$I_{dAV}$ ①	$T_C = 85^\circ\text{C}$ ; module	39	A		
$I_{TAVM}$	$T_C = 85^\circ\text{C}$ (180° sine; per thyristor)	16	A		
$I_{TSM}$	$T_{VJ} = 45^\circ\text{C}$ $V_R = 0$	200 210	A A		
	$t = 10 \text{ ms}$ (50 Hz) $t = 8.3 \text{ ms}$ (60 Hz)				
	$T_{VJ} = T_{VJM}$ $V_R = 0$	180 190	A A		
	$t = 10 \text{ ms}$ (50 Hz) $t = 8.3 \text{ ms}$ (60 Hz)				
$I^2t$	$T_{VJ} = 45^\circ\text{C}$ $V_R = 0$	200 150	$\text{A}^2\text{s}$ $\text{A}^2\text{s}$		
	$t = 10 \text{ ms}$ (50 Hz) $t = 8.3 \text{ ms}$ (60 Hz)				
	$T_{VJ} = T_{VJM}$ $V_R = 0$	160 150	$\text{A}^2\text{s}$ $\text{A}^2\text{s}$		
$(di/dt)_{cr}$	$T_{VJ} = T_{VJM}$ $f = 50 \text{ Hz}; t_p = 200 \mu\text{s}$ $V_D = \frac{2}{3} V_{DRM}$ $I_G = 0.15 \text{ A}$ $di_G/dt = 0.15 \text{ A}/\mu\text{s}$	repetitive; $I_T = 20 \text{ A}$  non repetitive; $I_T = I_{TAVM}$	100	$\text{A}/\mu\text{s}$	• Package with DCB ceramic base plate • Isolation voltage 3000 V~ • Planar passivated chips • Low forward voltage drop • Leads suitable for PC board soldering
$(dv/dt)_{cr}$	$T_{VJ} = T_{VJM}; V_D = \frac{2}{3} V_{DRM}$ $R_{GK} = \infty$ , method 1 (linear voltage rise)	500	$\text{V}/\mu\text{s}$		Applications
$V_{RGM}$		10	V		
$P_{GM}$	$T_{VJ} = T_{VJM}$ $I_T = I_{TAVM}$	$t_p = 30 \mu\text{s}$ $t_p = 300 \mu\text{s}$	$\leq 5$ $\leq 2.5$ 0.5	W	
$P_{GAVM}$				W	
$T_{VJ}$			-40...+125	$^\circ\text{C}$	
$T_{VJM}$			125	$^\circ\text{C}$	
$T_{stg}$			-40...+125	$^\circ\text{C}$	
$V_{ISOL}$	50/60 Hz, RMS $I_{ISOL} \leq 1 \text{ mA}$	$t = 1 \text{ min}$ $t = 1 \text{ s}$	2500 3000	$\text{V}_\sim$	
$M_d$	Mounting torque (M4)		1.5 - 2 14 - 18	Nm lb.in.	
<b>Weight</b>	Typ.	18	g		Advantages

Data according to IEC 60747 and refer to a single diode unless otherwise stated.

① for resistive load at bridge output.

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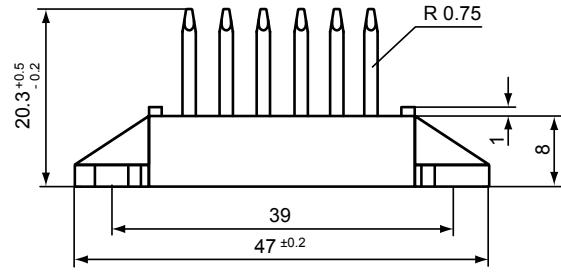
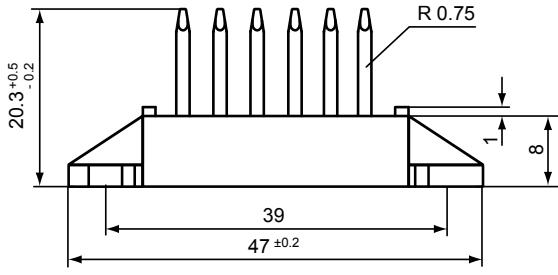
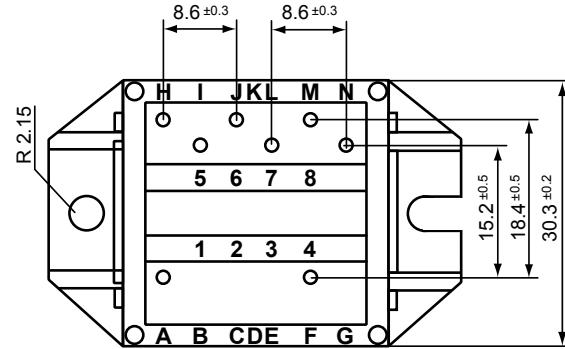
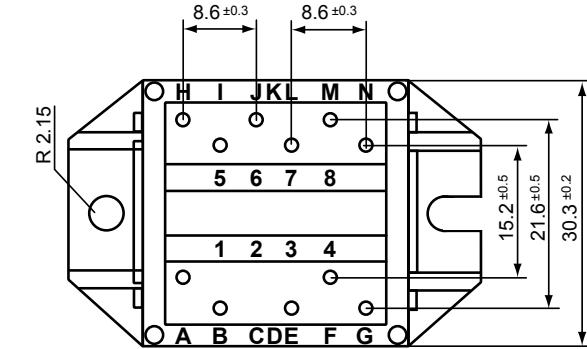
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Symbol	Conditions	Characteristic Values		
$I_D; I_R$	$V_R = V_{RRM}; V_D = V_{DRM}$	$T_{VJ} = T_{VJM}$	$\leq$	5 mA
$V_T$	$I_T = 20 \text{ A}$	$T_{VJ} = 25^\circ\text{C}$	$\leq$	1.6 V
$V_{TO}$	For power-loss calculations only	$T_{VJ} = 125^\circ\text{C}$	0.85	V
$r_T$			27	$\text{m}\Omega$
$V_{GT}$	$V_D = 6 \text{ V}$	$T_{VJ} = 25^\circ\text{C}$	$\leq$	1.5 V
		$T_{VJ} = -40^\circ\text{C}$	$\leq$	2.5 V
$I_{GT}$	$V_D = 6 \text{ V}$	$T_{VJ} = 25^\circ\text{C}$	$\leq$	25 mA
		$T_{VJ} = -40^\circ\text{C}$	$\leq$	50 mA
$V_{GD}$	$V_D = \frac{2}{3}V_{DRM}$	$T_{VJ} = T_{VJM}$	$\leq$	0.2 V
$I_{GD}$			$\leq$	3 mA
$I_L$	$t_p = 10 \mu\text{s}$ $I_G = 0.1 \text{ A}; di_G/dt = 0.1 \text{ A}/\mu\text{s}$	$T_{VJ} = 25^\circ\text{C}$	$\leq$	75 mA
$I_H$	$V_D = 6 \text{ V}; R_{GK} = \infty$	$T_{VJ} = 25^\circ\text{C}$	$\leq$	50 mA
$t_{gd}$	$V_D = \frac{1}{2}V_{DRM}$ $I_G = 0.1 \text{ A}; di_G/dt = 0.1 \text{ A}/\mu\text{s}$	$T_{VJ} = 25^\circ\text{C}$	$\leq$	2 $\mu\text{s}$
$R_{thJC}$	per thyristor / diode; DC		1.3	K/W
	per module		0.22	K/W
$R_{thJH}$	per thyristor / diode; DC		1.8	K/W
	per module		0.3	K/W
$d_s$	Creeping distance on surface		11.2	mm
$d_A$	Creepage distance in air		5	mm
$a$	Max. allowable acceleration		50	$\text{m}/\text{s}^2$

Dimensions in mm (1 mm = 0.0394")



VTO 39

VVZ 39

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